The data collected will be kept confidential and used by the Hongkong Bank Foundation/HSBC for the purposes set out in the Personal Information Collection Statement.

HSBC OVERSEAS SCHOLARSHIP 2023/24
APPLICATION FORM

APPLICANT'S PERSONAL INFORMATION

Family name: ____________ First name: ____________

Chinese name, if any: ____________ Preferred name: ____________

Birth date: ____________ Gender: N/A First 5 digits of HK I/D card: ____________

Are you a permanent Hong Kong citizen? Yes (If not born in Hong Kong*) *Place of birth: ____________ *No. of years living in HK: ____________

Home address: ____________

Contact number: ____________ Permanent e-mail: ____________

Parents' occupations: ____________

Monthly family[1] income[2] (HKD): ____________ No. of family members: ____________

Please affix recent photo here

If the total cost of your overseas study exceeds the maximum award possible under this scholarship (HKD300,000), please specify how you plan to fund the remaining costs.

____

Are you a recipient of a government grant? No Grant amount (HKD): ____________

Scholarship awards received, including any from HSBC (e.g. NAME OF SCHOLARSHIP, YEAR):

____

Do you have any overseas residency/ study abroad/ travelling experience? No If yes, please provide details below:

____

Name of local university: City University of Hong Kong Current year of study: ____________

Name of programme: ____________

GPA score: ____________ CGPA ____________ 2022/23 1st Term ____________ 2021/22 (if applicable)

ATTACH TRANSCRIPT

Name of target overseas university: ____________ Length of study: Full year

Choice of discipline at the overseas university: ____________

ENGLISH PROFICIENCY TEST

You only need to provide your scores for either of the tests.

Date of test (Tests must have been taken on **18 February 2021** or later in order to be valid):

TOEFL					
	Total Score (min 90)	Listening (min 22)	Writing (min 17)	Reading (min 21)	Speaking (min 21)
IELTS					
	Overall Band (min 6.5)	Listening (min 6.0)	Writing (min 6.0)	Reading (min 6.0)	Speaking (min 6.0)

Note: *To be eligible, your scores must be above the minimum stated above in each category.*

Name of secondary school or any other post-secondary school attended:

(Please list in chronological order from the most recent to the earliest.)

From	To	School

---

[1] "Family" means the applicant, applicant's spouse, parents, siblings, children and any other persons who are financially dependent on the aforementioned members.

[2] Please note that the applicant may be required to submit supporting documentation to substantiate his/her declaration.

Community service, if any.
(Please list a maximum of 3 in chronological order from the most recent to the earliest.)

From	To	Description

Work experience, if any.
(Please list a maximum of 3 in chronological order from the most recent to the earliest.)

From	To	Company /organisation	Title /capacity	Full-time/ part-time
				Full-time
				Full-time
				Full-time

PERSONAL ESSAY
INSTRUCTIONS: PLEASE ATTACH YOUR ANSWER TO THE ESSAY IN ENGLISH USING NO MORE THAN 500 WORDS.

Essay question: Please tell us about (1) your career aspirations and how an HSBC scholarship will open up a world of opportunity for you; and (2) your financial needs.

ADD PDF ATTACHMENT

DECLARATION BY THE APPLICANT

I, ______________________________ (Name in full), understand that I am required to disclose anything that may be considered to be an actual or potential conflict of interest with regard to my application for an HSBC Scholarship. Examples of potential conflicts of interest include, but are not limited to, previous or current student apprenticeships with HSBC and having close relatives[3] or individuals with whom the applicant has a personal relationship[4] with working in HSBC.

I declare that:

☐ I have no actual or potential conflict of interest that could directly or indirectly affect my application for an HSBC Scholarship. I will report such actual or potential conflict of interest should it arise.

☐ I have held the following position in HSBC and/or have a close relative or someone with whom I have a personal relationship with in HSBC. I provide the relevant information below for your assessment of conflict of interest:

☐ Student internship / placement in HSBC:

Department: ______________________________

Internship/ placement period: ______________________________

Name of supervisor: ______________________________

☐ Close relatives or those with whom the applicant has a personal relationship with working in HSBC:

Name: ______________________________

Job title: ______________________________

Relationship with the Applicant: ______________________________

Name: ______________________________

Job title: ______________________________

Relationship with the Applicant: ______________________________

☐ Any other actual or potential conflict of interest:

____

---

[3] "Close relative" means spouse, parents, step parents, siblings, step siblings, children, step children, grandparents or the spouse of any of these and aunts, uncles, nephews or nieces.

[4] "Personal relationship" means relationships with family members, friends and partnerships.

PERSONAL INFORMATION COLLECTION STATEMENT

Purpose of collection

The personal data provided in this form and any other information (the "Information") that may be provided for the purposes of the application for "HSBC Overseas Scholarship 2023/24" (the "Programme") and the enrolment for "The Hub for the Future" (the "Hub") will be used by the Hongkong Bank Foundation (the "Foundation") and The Hongkong and Shanghai Banking Corporation Limited ("HSBC") and their agents/contractors for one or more of the following purposes and any directly related purpose, in respect of the Programme and the Hub:

(i) to consider, process and administer your application, and serve any directly related purposes, e.g. processing and administering the scholarship under the Programme (if granted), and to communicate with you.

(ii) to be contacted by the Hub (if granted)
   a. to check, verify and maintain the Members' status;
   b. to keep and update the Members' contact records;
   c. to communicate with and provide updates and information to you;
   d. to inform you of or invite you to events, activities and programmes of or organised by the Hub or other events, activities and programmes considered by the Hub to be relevant to or of interest to Members;
   e. to compile statistics and conduct research of the operation of the Hub

(iii) any other purposes as may be required, authorised or permitted by any law and/or regulation.

It is voluntary for you to provide your personal data to the Foundation and HSBC. If you fail to supply any of the Information required by this form, your application may not be processed.

Access to personal data

Except where there is an exemption provided under the Personal Data (Privacy) Ordinance (Cap. 486), you have the right to request access to and correction of your personal data provided in this form when the data have not been erased. Your right of access includes the right to obtain a copy of your personal data provided in this form subject to payment of a fee.

Request and enquiry

Your request for access to personal data or enquiry regarding personal data privacy policy should be addressed to:

The Data Protection Officer
The Hongkong and Shanghai Banking Corporation Limited
PO Box 72677
Kowloon Central Post Office
Hong Kong
Re: HSBC Overseas Scholarship 2023/24
E-mail: dfv.enquiry@hsbc.com.hk

I declare that the Information provided in this Scholarship application is accurate, true and complete to the best of my knowledge. I am aware that the Hongkong Bank Foundation/HSBC will rely on such Information and consent to the Hongkong Bank Foundation/HSBC relying on the Information provided by me to determine my eligibility for the scholarship and the amount of the scholarship to be offered to me.

I confirm that I have carefully read and fully understand the “Personal Information Collection Statement” (the “PICS”) set out above. I accept the PICS and the purposes of use of the Information set out in it.

I confirm that each of the family members and other persons in respect of which the Information is provided in or in relation to this application (the “Relevant Person(s)”) has been notified of and agreed to the PICS and the purposes of use of the Information set out in it. I shall advise each Relevant Person that he/she has rights of access to, and correction of, his/her personal data. I agree to inform the Foundation/HSBC promptly in writing if I am not able or have failed to comply with the obligations set out in this paragraph in any respect.

I authorise and consent to my university releasing my personal data held by it to the Foundation/HSBC in order for it to use such information for such purposes set out in the PICS.

I authorise the Foundation to (i) transfer the Information to HSBC and for HSBC to use the Information for such purposes set out in the PICS; and (ii) release the results of my application to my university or institution.

Signature of the Applicant: ______________________________

Name in full: ______________________________

First 5 digits of HK I/D card no: ______________________________

Date: ______________________________

The data collected will be kept confidential and used by the Hongkong Bank Foundation/HSBC for the purposes set out in the Personal Information Collection Statement.

TO BE COMPLETED BY THE UNIVERSITY

SUPPLEMENTARY INFORMATION FROM UNIVERSITY (OPTIONAL)

UNIVERSITIES MAY ATTACH A ONE PAGE DOCUMENT TO PROVIDE ANY SUPPLEMENTARY INFORMATION ABOUT THE APPLICANT. (e.g. Recommendations from the university, personal qualities not captured by the form, any special learning needs, family background, etc.)

ADD PDF ATTACHMENT

I certify that the above-named applicant has been interviewed by our selection process and he/she is considered eligible for the Programme.

I understand that the information collected will be kept confidential and used by the Foundation/ HSBC to process the scholarship application and for the purposes set out in the PICS above. The Foundation/ HSBC will not disclose the information collected to any external organisation (other than as stated in the PICS attached in this document) unless we have the Applicant's and our consent or are required by law.

Signature: ____________________

(signature with official chop)

Date: ____________________

Name: ____________________

Title: ____________________

Official Chop

APPENDIX 3 - ATTACHMENT D

The data collected will be kept confidential and used by the Hongkong Bank Foundation/HSBC to process the scholarship application.

HSBC OVERSEAS SCHOLARSHIP 2023/24
STUDENT UNDERTAKING FORM

To be completed by applicant and guarantor/s

To: City University of Hong Kong
(name of university in Hong Kong)

In consideration of your awarding me the HSBC Overseas Scholarship, I, ______________________________,
(name in English)

______________________, the undersigned, hereby declare that the information I have submitted to the
(name in Chinese)

City University of Hong Kong and ______________________________
(name of university in Hong Kong) *(name of university outside Hong Kong)*

is accurate and I have no overseas residency / extensive studying experience.

In addition, I understand that the Scholarship will go towards tuition fees, a minimum economy return airfare, reasonable room and board costs, books and a small portion of living expenses, and I agree to:

1) Abide by the policies and requirements of both the local and overseas universities;
2) ***Participate in and complete the Hong Kong Young Ambassador Scheme***, a three-week full-time summer programme from mid-July to early August, organised by the Tourism Commission of the Hong Kong Special Administration Region Government and The Hong Kong Federation of Youth Groups, and to act as a goodwill ambassador for Hong Kong while abroad, ***or*** participate in an alternate programme similar to the Hong Kong Young Ambassador Scheme, with prior written approval from HSBC; and
3) Participate actively in campus life and the community while overseas.

Signed by

____
(Applicant)

In the presence of

____
(Signature of Witness)
(must be different from Guarantor)

Name: ______________________________

Address: ______________________________

____

Date: ______________________________

To be completed by Guarantor/s

In consideration of your accepting the above Undertaking from the applicant for the purposes stated thereon, I/we, the undersigned, hereby guarantee the due performance by the applicant of the Undertaking.

____
(Signature of Guarantor/s)

Name/s: ______________________________

Relationship: ______________________________

Address: ______________________________

____

Date: ______________________________

APPENDIX 3 - ATTACHMENT E

HSBC Overseas Scholarship 2023/24

Name of student:

Name of local university: City University of Hong Kong

Faculty/department:

Name of overseas university:

Length of study: *(commencement date / end date)*

Date of departure:

Submission date: *(Date of submission of this request)*

Expense	Name of foreign currency ([1] exchange rate)	HKD	Remarks (Please attach supporting materials: cost breakdown, etc.)
Tuition and fees (total number of credits to be taken:__________)	Amount recommended	Amount converted into HKD	
Room & board / accommodation / food (total number of weeks overseas: __________)			
Books and other supplies			
Eligible personal expenses (Please refer to Attachment C – guidelines)			
Lowest return air ticket			
Other items			
Total expenses during the term of study			
Recommended Total Scholarship Amount (HKD): (To be completed by school office) [1] Exchange rate should be obtained from https://www.hsbc.com.hk/zh-hk/investments/products/foreign-exchange/currency-rate/		Reviewed by : Name: Title: **(With university official chop)**	Signature

HSBC Overseas Scholarship 2023/24: LIST OF OVERSEAS UNIVERSITIES

IMPORTANT: HSBC does not have any arrangements with the below listed universities whereby HSBC Scholars will be guaranteed admission. Students are advised to pay the closest attention to application procedures and timeline to secure acceptance independent of HSBC.

Australia
Australian National University
Monash University
University of Adelaide
University of Melbourne
University of New South Wales
University of Queensland
University of Sydney

Canada
Dalhousie University
McGill University
McMaster University
Simon Fraser University
University of Alberta
University of British Columbia
University of Montreal
University of Toronto
University of Victoria

France
Ecole Normale Superieure, Paris
Ecole Polytechnique
ENS de Lyon
Pierre and Marie Curie Université

New Zealand
University of Auckland

Germany
Bielefeld University
Eberhard Karls University, Tübingen
Humboldt University of Berlin
Johann Wolfgang Goethe University Frankfurt am Main
Karlsruhe Institute of Technology
Ruprecht Karl University of Heidelberg
RWTH Aachen of Munich
Technical University of Munich
University of Bonn
University of Freiburg
University of Göttingen
University of Konstanz
University of Munich
University of Wurzburg

Netherlands
Delft University of Technology
Eindhoven University of Technology
Erasmus University Rotterdam

Netherlands (cont'd)
Leiden University
University of Amsterdam
University of Groningen
University of Twente
Utrecht University
VU University Amsterdam
Wageningen University and Research Center

UK/Ireland
Lancaster University
London School of Economics & Political Science
Newcastle University
University of Aberdeen
University of Birmingham
University of Bristol
University of Cambridge
University of Dundee
University of Durham
University of Edinburgh
University of Exeter
University of Glasgow
University of Leeds
University of Liverpool
University of London (Birkbeck , Imperial College, King's College, Queen Mary, University College, Royal Holloway)
University of Manchester
University of Nottingham
University of Oxford
University of Sheffield
University of Southampton
University of St Andrews
University of Sussex
University of York

USA
Arizona State University
Boston College
Boston University
Brown University
California Institute of Technology
Carnegie Mellon University
Case Western Reserve University
Columbia University
Cornell University
Dartmouth College
Drexel University
Duke University
Emory University

USA (cont'd)
George Washington University
Georgetown University
Georgia Institute of Technology
Harvard University
Indiana University
Iowa State University
Johns Hopkins University
Kent State University
Massachusetts Institute of Technology
Medical College of Georgia
Michigan State University
New York University
Northwestern University
Ohio State University
Princeton University
Purdue University
Rensselaer Polytechnic Institute
Rice University
Stanford University
Stony Brook University
Tufts University
University of Arizona
University of California, Berkeley
University of California, Davis
University of California, Irvine
University of California, Los Angeles
University of California, Riverside
University of California, San Diego
University of California, Santa Barbara
University of California, Santa Cruz
University of Chicago
University of Cincinnati
University of Colorado
University of Delaware
University of Hawaii
University of Illinois – Chicago
University of Illinois – Urbana -Champaign
University of Iowa
University of Maryland College Park
University of Massachusetts
University of Michigan
University of Minnesota
University of North Carolina, Chapel Hill
University of Notre Dame
University of Pennsylvania
University of Pittsburgh
University of Southern California
University of Utah
University of Virginia
University of Washington
University of Wisconsin
Vanderbilt University
Wake Forest University
Washington University Saint Louis
William & Mary
Yale University

Switzerland
École Polytechnique Federale of Lausanne
Swiss Federal Institute of Technology Zurich
University of Basel
University of Geneva
University of Lausanne
University of Zurich

Sweden
Karolinska Institutet
Lund University
Royal Institute of Technology
Stockholm University
Swedish University of Agricultural Sciences
Uppsala University

Rest of Europe
Aarhus University (Denmark)
Catholic University of Leuven (Belgium)
Ghent University (Belgium)
Bocconi University (Bologna, Italy)
Erasmus University (Netherlands)
Pompeu Fabra University (Spain)
Technical University of Denmark
University of Barcelona (Spain)
University of Bergen (Norway)
University of Copenhagen
University of Helsinki (Finland)
University of Innsbruck (Austria)
University of Vienna (Austria)

APPENDIX 3 - ATTACHMENT C

GUIDELINES ON HOW TO CALCULATE AN OVERSEAS SCHOLARSHIP AWARD AMOUNT

*The university/institution will be responsible for authenticating the recommended scholarship amount

CATEGORY	TYPE OF EXPENSE	ELIGIBLE?	REMARKS
Tuition	Tuition fees	YES	Must be supported by evidence from the overseas university outlining the duration of the academic year and confirming the number of credits that the student will take during his/her one year or one semester abroad. The information provided will be regarded as final and costs of any additional credits taken during the academic year will not be covered.
	Subscriptions, student association fees, registration fees	YES	The following two conditions must be met: (1) fees are mandatory; (2) fees are non-refundable
Room & board / Accommodation / Meals	Room	YES	The student should opt for shared/ the most basic on-campus accommodation. If on-campus accommodation is not available, the overseas university should recommend an alternate arrangement and provide an estimate of the associated costs. The period covered is the duration of the academic year (or the single semester if applicable). This can include any breaks and holidays that occur during the academic year (or semester if applicable). If the student is required to attend a mandatory orientation prior to the academic year or semester, room costs for that period (as recommended by the overseas university) is also eligible.
	Board	YES	The student should opt for campus residence that provides full catering service. If this is not possible, the overseas university should recommend an alternate arrangement and provide an estimate of meal costs. If more than one meal plans are offered, the student may opt for the most comprehensive plan.
Books & other supplies	Books, supplies and stationery	YES	The overseas university should recommend an amount for the cost of these items.
	Lab/ studio fees; apparatus; uniform	YES	Eligible if recommended by the overseas university and required by the student's degree course.
Living/ personal expenses	Laundry	YES	For coin-operated machines only.
	Police registration fee	YES	Eligible only if mandatory

	Energy charges	YES	Eligible only if the student lives off-campus or if charges are not included in room costs.
	Transportation	YES	For public transportation and travel to and from university during school days. Travelling costs associated with mandatory clinical placement(s) are eligible.
	Telephone charges	NO	
	Internet charges	YES	Includes installation and rental charges only depending on accommodation.
	Social functions and entertainment	NO	
	Sight-seeing and personal travel	NO	
	Deposit fees	NO	
	Insurance (travel, medical, dental, or personal possession)	NO	
	Personal hygiene, toiletries & cleaning materials	NO	
	TV rental and license/ cable costs	NO	
	Clothes	NO	
	Cultural programmes / student events	NO	
	Owning/ renting a vehicle	NO	
Airfare	Economy return airfare	YES	For a **minimum** economy return airfare. The student should request the least expensive routing. Must be supported by three quotations from different travel agents. Include at least two different carriers and indicate the expected date of departure from Hong Kong. Inclusive of any applicable government and airport taxes and security levy.
Miscellaneous	Other student fees not indicated as compulsory	NO	
	Student visa application fees	YES	